# 2-146483-6 - ACTIVE

### AMPMODU | AMPMODU Headers

TE Internal #: 2-146483-6 PCB Mount Header, Vertical, Board-to-Board, 52 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin-Lead, Through Hole - Solder, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



## PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **52** 

Number of Rows: 2

## Features

## Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Breakaway

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	52
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 ΜΩ
Body Features	
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	2.79 mm[.109 in]
Mating Square Post Dimension	.64 mm[.025 in]

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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Underplating Material Thickness	1.27 μm[50 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Tin-Lead
Contact Mating Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.3 mm[.13 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	5.08 mm[.2 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Assembly Process Feature	None
Circuit Application	Signal

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### **Industry Standards**

Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Package
<b>Product Compliance</b> For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Not Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) SVHC > Threshold: Pb (13% in Component Part)

Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Solder Process Capability

Not Low Halogen - contains Br or Cl > 900 ppm.

Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**

PCB Mount Header, Vertical, Board-to-Board, 52 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin-Lead, Through Hole - Solder, AMPMODU Headers



TE Part # 7-146486-6 52 MODII HDR DRST UNSHRD STKG

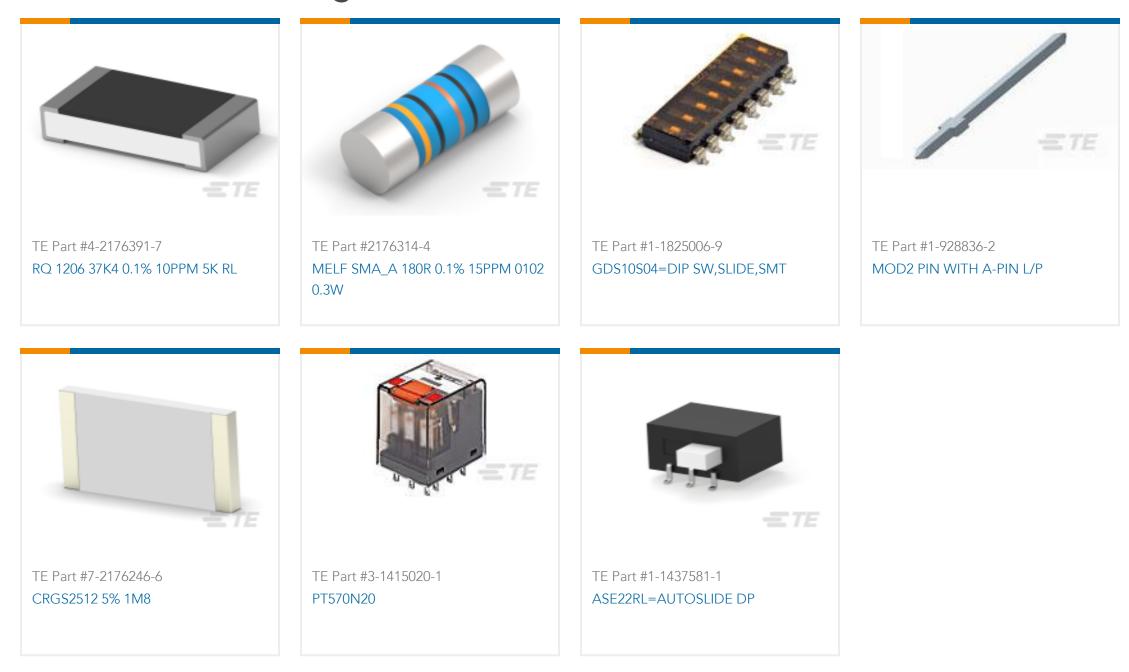
## Also in the Series AMPMODU Headers





Wire-to-Board Connector Contacts(65)

## Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 52 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin-Lead, Through Hole - Solder, AMPMODU Headers



## Documents

Product Drawings 52 MODII HDR DRST UNSHRD STKG

English

## **CAD** Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_2-146483-6\_A\_c-2-146483-6-a.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_2-146483-6\_A\_c-2-146483-6-a.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_2-146483-6\_A\_c-2-146483-6-a.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU Interconnetion System

AMPMODU Interconnetion System

English